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March 2013

## FSA2467 0.4Ω Low-Voltage Dual DPDT Analog Switch

#### **Features**

- Typical 0.4Ω On Resistance (R<sub>ON</sub>) for +2.7V Supply
- Features Less then12μA Iccτ Current when Sn Input is Lower than V<sub>CC</sub>
- 0.25Ω Maximum R<sub>ON</sub> Flatness for +2.7V Supply
- 3 x 3mm 16-Lead MLP Package
- 1.8x2.6mm 16-Lead UMLP Package
- Broad V<sub>CC</sub> Operating Range
- Low THD (0.02% Typical for 32Ω Load)

### **Applications**

- Cell Phone
- PDA
- Portable Media Player

### Description

The FSA2467 is a dual Double-Pole, Double-Throw (DPDT) analog switch. The FSA2467 operates from a single 1.65V to 4.3V supply. The FSA2467 features an ultra-low on resistance of  $0.4\Omega$  at a +2.7V supply and 25°C. This device is fabricated with sub-micron CMOS technology to achieve fast switching speeds and is designed for break-before-make operation.

FSA2467 features very low quiescent current even when the control voltage is lower than the  $V_{\rm CC}$  supply. This feature allows mobile handset applications direct interface with baseband processor general-purpose  $I/O_{\rm S}$ 

### **Ordering Information**

Part Number	Top Mark	Package Description
FSA2467MPX	FSA 2467	16-lead Molded Leadless Package (MLP), JEDEC MO-220, 3 x 3mm Square
FSA2467UMX	GC	16-lead Ultrathin Molded Leadless Package (UMLP), 1.8 x 2.6mm

### **Application Diagram**

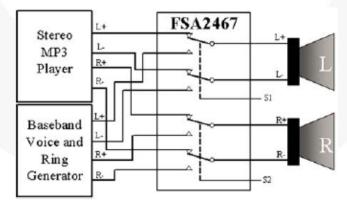


Figure 1. Application Diagram

### **Pin Assignments**

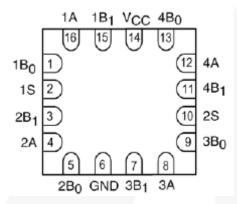


Figure 2. MLP (Top Through View)

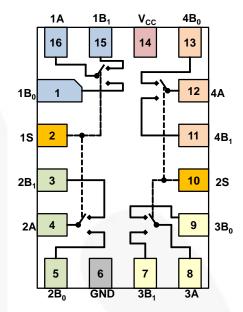


Figure 3. UMLP (Top View)

#### **Truth Table**

Control Inputs	Function
LOW	nB <sub>0</sub> Connected to nA
HIGH	nB <sub>1</sub> Connected to nA

### **Pin Descriptions**

Name	Function
nA, nB <sub>0</sub> , nB <sub>1</sub>	Data Ports
nS	Control Input

### **Analog Symbol**

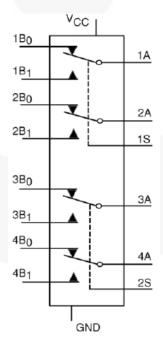


Figure 4. Analog Symbol

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Paramete	r	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	5.0	V
Vs	Switch Voltage		-0.5	V <sub>CC</sub> +0.3	V
V <sub>IN</sub>	Input Voltage		-0.5	5.0	V
I <sub>IK</sub>	Input Diode Current		-50		mA
I <sub>SW</sub>	Switch Current			350	mA
I <sub>SWPEAK</sub>	Peak Switch Current (Pulsed at 1ms du	uration, <10% Duty Cycle)		500	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
$T_J$	Junction Temperature		/	+150	°C
TL	Lead Temperature, Soldering 10 Secon	nds		+260	°C
ESD	Electrostatic Discharge Capability	Human Body Model, JESD22-A114	\	5.5	kV

### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	1.65	4.30	V
$V_{IN}$	Control Input Voltage <sup>(1)</sup>	0	V <sub>CC</sub>	V
Vs	Switch Input Voltage	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

#### Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

#### **DC Electrical Characteristics**

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Condition	V <sub>cc</sub> (V)	T	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85°C	
<b>-</b>		Condition	•66(•)	Min.	Тур.	Max.	Min	Max.	Unit
			4.3				1.4		
$V_{IH}$	Input Voltage High		2.7 to 3.6				1.3		V
VIH	input voltage riigii		2.3 to 2.7				1.1		<b>v</b>
			1.65 to 1.95				0.9		
			4.3					0.7	
V	Input Valtage Levy		2.7 to 3.6					0.5	V
$V_{IL}$	Input Voltage Low		2.3 to 2.7					0.4	V
			1.65 to 1.95		- //			0.4	Ì
I <sub>IN</sub>	Control Input Leakage	V <sub>IN</sub> =0V to V <sub>CC</sub>	1.65 to 4.30				-0.5	0.5	μA
I <sub>NO(OFF)</sub>	Off Leakage Current of	nA=0.3V, V <sub>CC</sub> -0.3V							
I <sub>NC(OFF)</sub> Port nB <sub>0</sub> and nB <sub>1</sub>		nB <sub>0</sub> or nB <sub>1</sub> =0.3V, V <sub>CC</sub> -0.3V or floating	1.95 to 4.30	-10	10	10	-50	50	nA
On Leakage	On Leakage Current of	nA=0.3V,V <sub>CC</sub> -0.3V	4.05 +- 4.20	40		40	50	50	0
I <sub>A(ON)</sub>	Port A	nB₀ or nB₁=0.3V, V <sub>cc</sub> - 0.3V or Floating		-10		10	-50	50	nA
		I <sub>OUT</sub> =100mA	4.3		0.4			0.6	
	Cuitab Or	nB <sub>0</sub> or nB <sub>1</sub> =0V,0.8V, 1.8V,2.7V	2.7		0.4			0.6	17
R <sub>on</sub>	Switch On Resistance <sup>(2)</sup>	I <sub>OUT</sub> =100mA, nB <sub>0</sub> or nB <sub>1</sub> =0V,0.7V, 1.2V, 2.3V	2.3	0.55				0.95	Ω
		I <sub>OUT</sub> =100mA, nB <sub>0</sub> or nB <sub>1</sub> =1.0V	1.8	0.8		1		2.0	/
$\Delta R_{ m ON}$	On Resistance Matching Between	I <sub>OUT</sub> =100mA, nB <sub>0</sub> or nB <sub>1</sub> =0.8V	2.7	0.04				0.10	Ω
AINON	Channels <sup>(3)</sup>	$I_{OUT}$ =100mA, $nB_0$ or $nB_1$ =0.7V	2.3	0.03				0.10	12
D	On Resistance	I <sub>OUT</sub> =100mA, B <sub>0</sub> or	2.7					0.25	Ω
R <sub>FLAT(ON)</sub>	Flatness <sup>(4)</sup>	nB <sub>1</sub> =0V to V <sub>CC</sub>	2.3					0.3	12
$I_{CC}$	Quiescent Supply Current	V <sub>IN</sub> =0V to V <sub>CC</sub> I <sub>OUT</sub> =0V	4.3	-100		100	-500	500	nA
I <sub>CCT</sub>	Increase in I <sub>CC</sub> Current	V <sub>IN</sub> =1.8V	4.3		7	12		15	μA
•001	per Control Voltage	V <sub>IN</sub> =2.6V	4.3		3	6		7	μ, τ

#### Notes:

- 2. On resistance is determined by the voltage drop between A and B pins at the indicated current through the switch.
- $\Delta$  R<sub>ON</sub>=R<sub>ON max</sub> R<sub>ON min</sub> measured at identical V<sub>CC</sub>, temperature and voltage. Flatness is defined as the difference between the maximum and minimum value of on resistance over the specified range of conditions.

### **AC Electrical Characteristics**

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Condition	V <sub>cc</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85°C		Unit	Figure
•			- 66	Min.	Тур.	Max.	Min.	Max.		
		nB0 or nB1=1.5V	3.6 to 4.3			50		60		
$t_{\text{ON}}$	Turn-On Time	R <sub>L</sub> =50Ω, C <sub>L</sub> =35pF	2.7 to 3.6			65		75	ns	Figure 8
			2.3 to 2.7	14		80		90		
		nB0 or nB1=1.5V	3.6 to 4.3			32		40		
$t_{OFF}$	Turn-Off Time	R <sub>L</sub> =50Ω, C <sub>L</sub> =35pF	2.7 to 3.6			42		50	ns	Figure 8
			2.3 to 2.7			52		60		
		nB0 or nB1=1.5V	3.6 to 4.3		12		4			
$t_{BBM}$	Break-Before- Make Time	R <sub>L</sub> =50Ω, C <sub>L</sub> =35pF	2.7 to 3.6		15	- 1/			ns	Figure 9
		2.3 to 2	2.3 to 2.7		20					
		$C_L=100pF,$ $V_{GEN}=0V,$ $R_{GEN}=0\Omega$	3.6 to 4.3		15					
Q	Q Charge Injection	$C_L=100pF,$ $V_{GEN}=0V,$ $R_{GEN}=0\Omega$	2.7 to 3.6		10		Y.		pC	Figure 11
		C <sub>L</sub> =100pF, V <sub>GEN</sub> =0V, R <sub>GEN</sub> =0Ω	2.3 to 2.7		8					
£1	1/2		3.6 to 4.3		-75				dB	Figure 10
OIRR	Off Isolation	f=100KHz, R <sub>L</sub> =50Ω,C <sub>L</sub> =5pF	2.7 to 3.6		-75		ı			
		Ν[-3022,Ο[-3β1	2.3 to 2.7		-75					
			3.6 to 4.3		-75					
Xtalk	Crosstalk	f=100KHz, $R_L$ =50 $\Omega$ , $C_L$ =5pF	2.7 to 3.6		-75				dB	Figure 10
		C[=3hL	2.3 to 2.7		-75					
BW	-3dB Bandwidth	R <sub>L</sub> =50Ω	2.3 to 4.3		85			1	MHZ	Figure 1
THD Total Harmonic Distortion	$R_L$ =32 $\Omega$ , $V_{IN}$ =2 $V_{PP}$ , f=20 to 20kHZ	3.6 to 4.3		0.02		1				
		$R_L$ =32 $\Omega$ , $V_{IN}$ =2 $V_{PP}$ , f=20 to 20kHZ	2.7 to 3.6		0.02				%	Figure 14
		$R_L$ =32 $\Omega$ , $V_{IN}$ =2 $V_{PP}$ , $f$ =20 to 20kHZ	2.3. to 2.7		0.02					

### Capacitance

Symbol	Parameter	Condition	V <sub>cc</sub>	T <sub>A</sub> = +25°C Typical	Unit	Figure
C <sub>IN</sub>	Control Pin Input Capacitance	f=1MHZ	0	1.5	pF	Figure 8
C <sub>OFF</sub>	B Port Off Capacitance	f=1MHZ	3.3	32	pF	Figure 8
C <sub>ON</sub>	A Port On Capacitance	f=1MHZ	3.3	118	pF	Figure 8

### **Typical Applications**

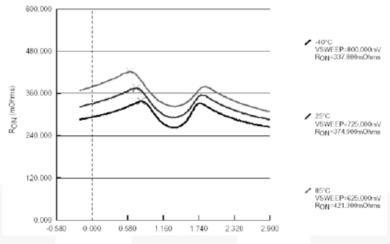


Figure 5.  $R_{ON}$  at 2.7V  $V_{CC}$ 

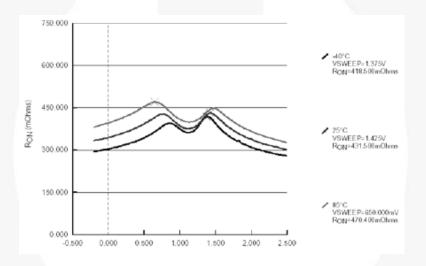
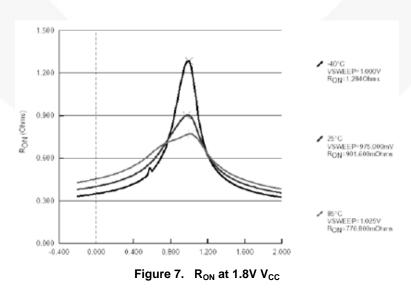
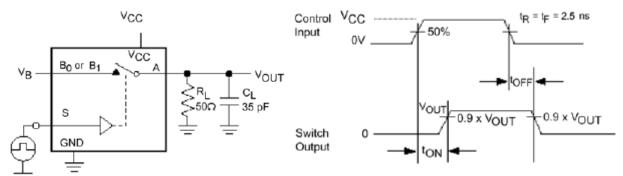


Figure 6. R<sub>ON</sub> at 2.3V V<sub>CC</sub>



### **AC Loadings and Waveforms**



C<sub>L</sub> includes Fixture and Stray Capacitance

Logic Input Waveforms Inverted for Switches that have the Opposite Logic Sense

Figure 8. Turn-On / Turn-Off Timing

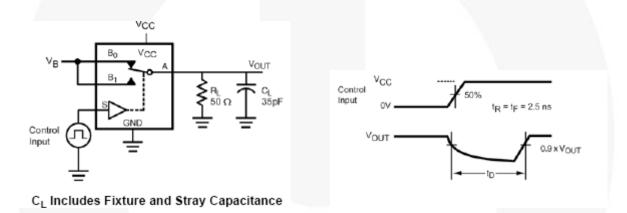


Figure 9. Break-Before-Make Timing

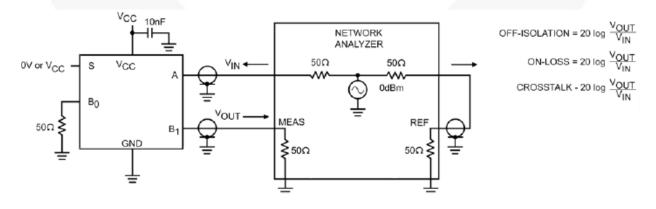


Figure 10. Off Isolation and Crosstalk

### AC Loadings and Waveforms (Continued)

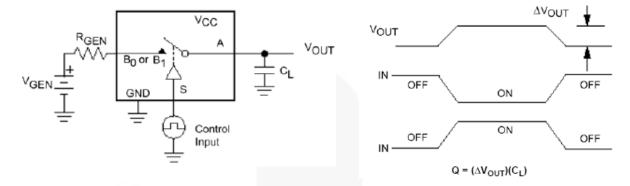


Figure 11. Charge Injection

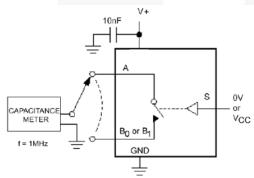


Figure 12. On / Off Capacitance Measurement Setup

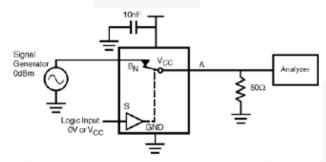


Figure 13. Bandwidth

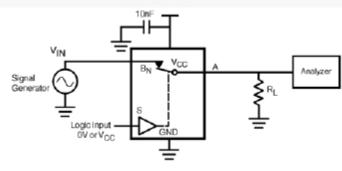
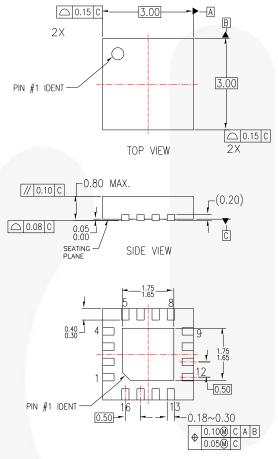


Figure 14. Harmonic Distortion

### **Package Dimensions**



(1.75) (3.30) (3.30) (2.16) (3.30) (3

RECOMMENDED LAND PATTERN

BOTTOM VIEW

#### NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-220, VARIATION WEED-Pending, DATED pending
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. DIMENSIONS ARE EXCLUSIVE OF BURS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

MLP16BrevB

Figure 15. 16-Lead, Molded Leadless Package (MLP), JEDEC MO-220 3x3mm Square

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: http://www.fairchildsemi.com/packaging/3x3MLP16 Pack TNR.pdf.

-0.563 (15X)

0.50

0.30<sub>15</sub>X

0.50

R0 20 -PACKAGE

**EDGE** 

NON-PIN 1

NON-PIN 1

**LEAD** 

**OPTION 2** 

SCALE: 2X

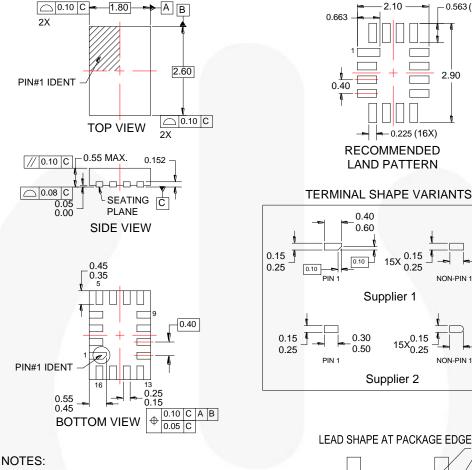
**LEAD** 

**OPTION 1** 

SCALE: 2X

2.90

### **Package Dimensions**



- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY.
- E. DRAWING FILENAME: MKT-UMLP16Arev4.
- F. TERMINAL SHAPE MAY VARY ACCORDING TO PACKAGE SUPPLIER, SEE TERMINAL SHAPE VARIANTS.

#### Figure 16. 16-Lead, Ultrathin Molded Leadless Package (UMLP)

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Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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